

Product Information Sheet

MATERIAL ID:

EPO-TEK® OG178

Date: Nov 2010

Per:

Rev: III

Material Description:

A single component, UV/visible shifted light curable epoxy, designed for adhesive, sealing, coating and encapsulating applications found in semiconductor, electro-optics, fiber optics, medical, and scientific/OEM industries. It is a low viscosity, all-purpose adhesive.

Number of Components:

Single

Mix Ratio by weight:

N/A

Cure Schedule (minimum)*

100mW/cm² for >3 minutes @ 320-500 nm (depending on thickness)

Specific Gravity:

1.15 --- Part A: Part B:

Pot Life:

N/A

Shelf Life:

One year refrigerated

NOTE: Container(s) should be kept closed in a dark location when not in use.

*Please see Applications Note(s) available on our website.

MATERIAL CHARACTERISTICS: *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.*

* denotes test on lot acceptance basis; Cure condition: varies as required

PHYSICAL PROPERTIES:			
*Color (before cure):	Clear Amber	Die Shear @ 23°C:	≥ 10 Kg / 3,400 psi
*Consistency:	Pourable liquid	Degradation Temp:	296 °C
*Viscosity (23°C):		Weight Loss:	
@ 100 rpm	300 - 600 cPs	@ 200°C:	2.45 %
Thixotropic Index:	N/A	@ 250°C:	3.19 %
*Glass Transition	≥ 50 °C (Post-Cure)	@ 300°C:	
Dynamic Scan 20—200°C; Ramp -10—200°C @ 20°C/Min)		Operating Temp:	
Coefficient of Thermal Expansion (CTE):		Continuous:	- 55°C to + 125°C
Below Tg:	68 x 10 ⁻⁶ in/in°C	Intermittent:	- 55°C to + 225°C
Above Tg:	185 x 10 ⁻⁶ in/in°C	Storage Modulus @ 23°C:	220,734 psi
Shore D Hardness:	86	*Particle Size:	N/A

OPTICAL PROPERTIES @ 23°C:	
Spectral Transmission:	>99 % @ 541-1660 nm >95 % @ 380-520 nm
Refractive Index (uncured):	1.528 @ 589 nm